

40V N-Channel MOSFET

General Features

- Proprietary New Trench Technology
- Ultra-low Miller Charge
- $R_{DS(ON),typ.}$ =1.3 m $\Omega @V_{GS}$ =10V
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

Applications

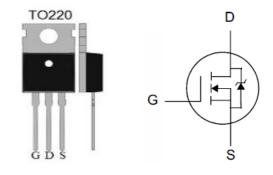
- High efficiency DC/DC Converters
- Synchronous Rectification
- Motor Drive

Ordering Information

Part Number	Package	Brand
PTP01N04N	TO-220	Z

Lead Free Package and Finish

BV _{DSS}	R _{DS(ON),typ.}	I _D ^[2]
40V	$1.3 m\Omega$	345A



T_C=25 ℃ unless otherwise specified

Absolute Maximum Ratings

Symbol	Parameter	PTP01N04N	Unit	
V _{DSS}	Drain-to-Source Voltage ^[1]	40	V	
V _{GSS}	Gate-to-Source Voltage	±20	7 '	
	Continuous Drain Current ^[2] V _{GS} @ 10V	345		
I_D	Continuous Drain Current ^[3] V _{GS} @ 10V	196	۸	
Continuous Drain Current ^[2] T _C = 100°C, V _{GS} @		244	Α	
I _{DM}	Pulsed Drain Current at V _{GS} =10V ^[2,4]	1380		
E _{AS}	Single Pulse Avalanche Energy(L=1Mh,	2000	mJ	
dv/dt	Peak Diode Recovery dv/dt ^[3]	5.0	V/ns	
D	Power Dissipation	375	W	
P_{D}	Derating Factor above 25℃	2.5	W/°C	
T _L T _{PAK}	Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10 seconds, Package Body for 10 seconds	300 260	$^{\circ}$	
T _J & T _{STG}	Operating and Storage Temperature Range	-55 to 175		

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics Maximum Ratings

Symbol	Parameter	PTP01N04N	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	0.4	20
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	°C/ W



Electrical Characteristics

OFF Characteristics T_J =25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	40			٧	V _{GS} =0V, I _D =250uA
I _{DSS} Drain-to-Source L	Durin to On and Lord and On and			1	uA	V _{DS} =40V, V _{GS} =0V
	Drain-to-Source Leakage Current			100		V_{DS} =32V, V_{GS} =0V, T_J =125°C
I _{GSS} Ga	Gate-to-Source Leakage Current			+100	nA	V _{GS} =+20V, V _{DS} =0V
				-100	11/4	V _{GS} =-20V, V _{DS} =0V

ON Characteristics

T_J =25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
R _{DS(ON)}	Static Drain-to-Source On-Resistance		1.3	1.5	mΩ	V _{GS} =10V, I _D =196A ^[3]
$V_{GS(TH)}$	Gate Threshold Voltage	2.0		4.0	V	V _{DS} =V _{GS} , I _D =250uA

Dynamic Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Con	ditions
C _{iss}	Input Capacitance		10.8			\/ -0\	
C _{rss}	Reverse Transfer Capacitance		0.9		nF	V_{GS} =0V, V_{DS} =25V, f =1.0MH $_{Z}$	
C _{oss}	Output Capacitance		1.6				
Rg	Gate Series Resistance		2.0		Ω	f=1.0MH _Z	
	Total Cata Charge		148			V _{GS} =0 to 10V	
Q_g	Total Gate Charge		88				V _{DD} =20V,
Q _{gs}	Gate-to-Source Charge		35		nC	V _{GS} =4.5V I _D =185A,	
Q_{gd}	Gate-to-Drain (Miller) Charge		42				

Resistive Switching Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
td(ON)	Turn-on Delay Time		29		nS	V _{DD} =26V, I _D =195A,
trise	Rise Time		30			
td(OFF)	Turn-Off Delay Time		145			V_{GS} = 10V RG=2.1 Ω
t fall	Fall Time		43			



Source-Drain Body Diode Characteristics

T_J=25 °C unless otherwise specified

Symbol	Parameter	Min	Тур.	Max.	Unit	Test Conditions	
I _{SD}	Continuous Source Current ^[2]	-		345	۸	Integral PN-diode in MOSFET	
I _{SM}	Pulsed Source Current ^[2]			1380	Α		
V_{SD}	Diode Forward Voltage			1.3	V	I _S =195A, V _{GS} =0V	
trr	Reverse recovery time	1	81		nS		
trr	Reverse recovery time, T _J = 125°C		85		113	V _R =34V,V _{GS} =0V ,I _F =195A, dir/dt=100A/μs	
Qrr	Reverse recovery charge		70		nC		
QII	Reverse recovery charge, T _J = 125°C		83		IIC		
IRRM	Reverse Recovery Current	-	1.7		Α		

Note:

^[2] Silicon limited current only.
[3] Package limited current.
[4] Repetitive rating; pulse width limited by maximum junction temperature.
[5] Pulse width≤380µs; duty cycle≤2%.



Typical Characteristics

Figure 1. Maximum Transient Thermal Impedance

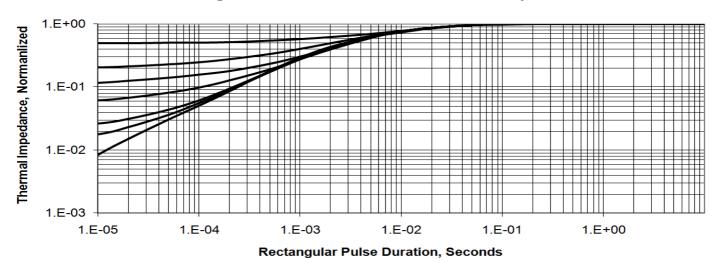


Figure 2. Maximum Power Dissipation vs **Case Temperature**

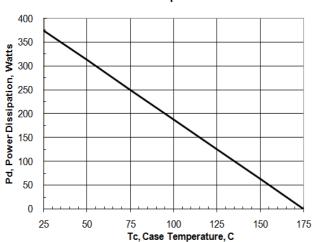


Figure 4. Typical Output Characteristics

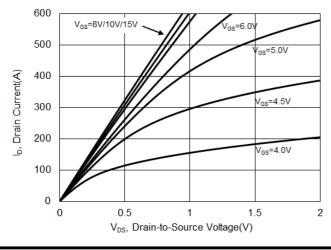


Figure 3 .Maximum Continuous Drain Current vs Case Temperature

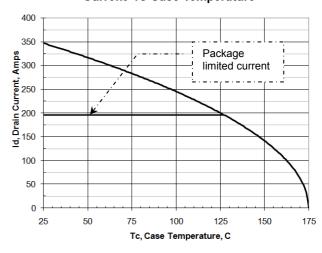
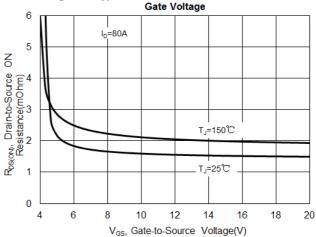


Figure 5. Typical Drain-to-Source ON Resistance vs.





Typical Characteristics(Cont.)

Figure 6. Peak Current Capability

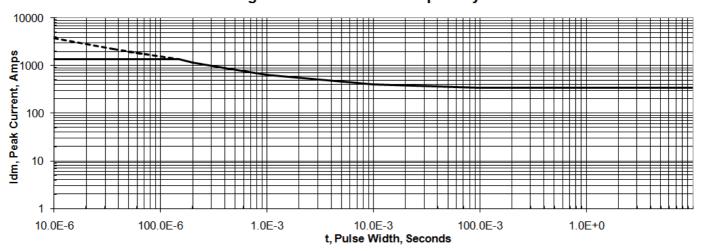
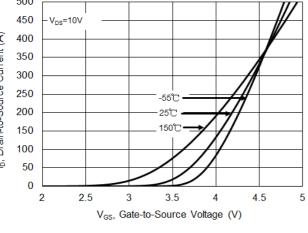
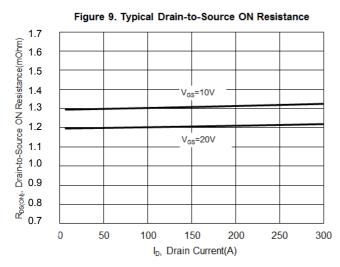
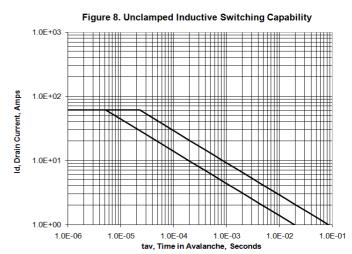
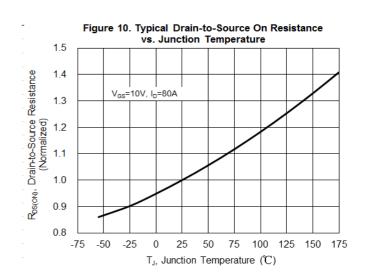


Figure 7. Typical Transfer Characteristics 500 450 Ip, Drain-to-Source Current (A) 400 350 300 250 200 150 100 50 0 2 2.5 4.5 3.5











Typical Characteristics(Cont.)

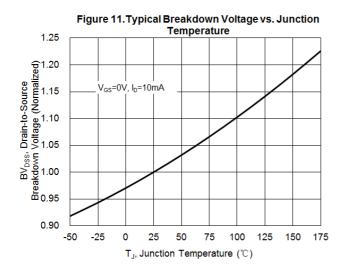


Figure 13 . Maximum Safe Operating Area

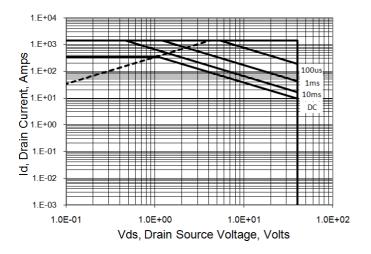


Figure 15 . Typical Gate Charge

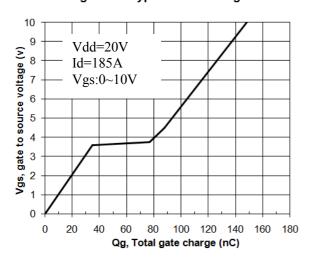
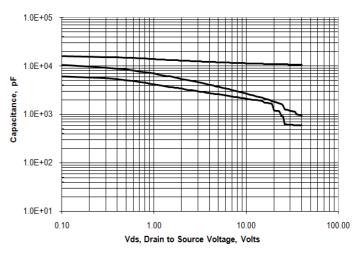
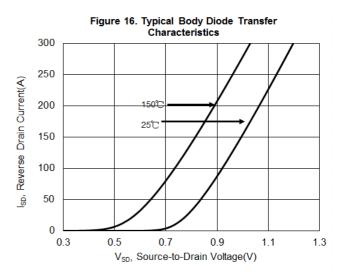


Figure 14. Capacitance vs Vds

T₁, Junction Temperature (°C)







Test Circuits and Waveforms

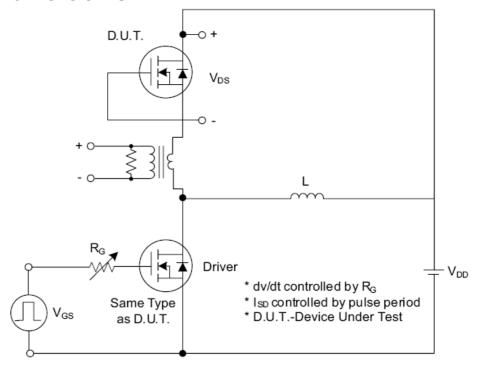


Fig. 1.1 Peak Diode Recovery dv/dt Test Circuit

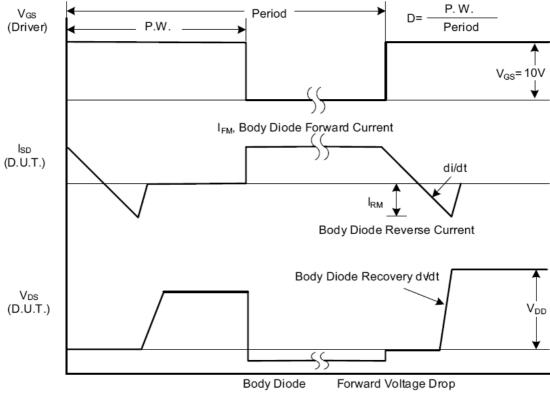


Fig. 1.2 Peak Diode Recovery dv/dt Waveforms



Test Circuits and Waveforms (Cont.)

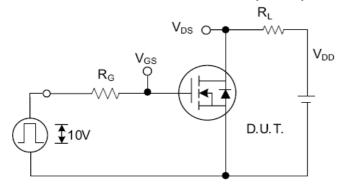


Fig. 2.1 Switching Test Circuit

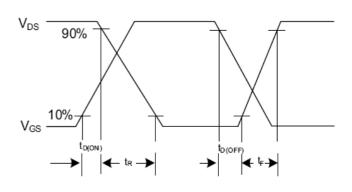


Fig. 2.2 Switching Waveforms

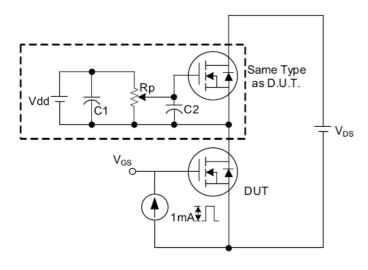


Fig. 3 . 1 Gate Charge Test Circuit

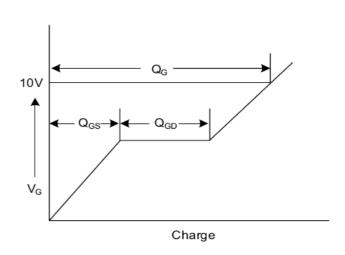


Fig. 3.2 Gate Charge Waveform

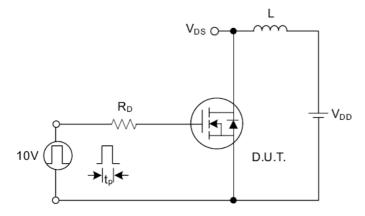


Fig. 4.1 Unclamped Inductive Switching Test Circuit

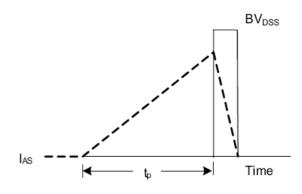


Fig. 4.2 Unclamped Inductive Switching Waveforms



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